

Title (en)

Cleaning composition, cleaning method, and manufacturing method of semiconductor device

Title (de)

Reinigungszusammensetzung, Reinigungsverfahren und Herstellungsverfahren für ein Halbleiterbauelement

Title (fr)

Composition de nettoyage, procédé de nettoyage, et procédé de fabrication d'un dispositif à semi-conducteur

Publication

**EP 1892285 B1 20100106 (EN)**

Application

**EP 07114451 A 20070816**

Priority

JP 2006224759 A 20060821

Abstract (en)

[origin: EP1892285A2] A cleaning composition can decontaminate a surface of a chemically mechanically polished semiconductor substrate having a metal wiring and a low dielectric constant film and can highly remove impurities such as residual abrasive grains, residual polishing waste, and metal ions on the metal wiring and low dielectric constant film without corroding the metal wiring, degrading electric characteristics of the low dielectric constant film, and causing mechanical damage to the low dielectric constant film. A cleaning method of a semiconductor substrate uses the cleaning composition, and a manufacturing method of a semiconductor substrate includes a step of performing the cleaning method. The cleaning composition is used for a chemically mechanically polished surface, and includes organic polymer particles (A) having a crosslinked structure and an average dispersed particle diameter of 10 nm or more and less than 100 nm, and a complexing agent (B).

IPC 8 full level

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CPC (source: EP US)

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Cited by

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DE FR IT

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**EP 1892285 A2 20080227**; **EP 1892285 A3 20080305**; **EP 1892285 B1 20100106**; DE 602007004153 D1 20100225; JP 2008047842 A 20080228; JP 4912791 B2 20120411; TW 200811282 A 20080301; TW I411679 B 20131011; US 2008045016 A1 20080221

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